N4000-6 (FC) BC®

Buried Capacitance, High-T_g Multifunctional Epoxy Laminate & Buried Capacitance, Fast Cure, High-T_g Multifunctional Epoxy Laminate



N4000-6 (FC) is a high- T_g FR-4 epoxy that provides a wide range of performance versatility and ease of processing. Offering a greater degree of freedom of design for smaller, more reliable assemblies, N4000-6 (FC) BC® is offered as a buried capacitance solution. N4000-6 (FC) BC® is engineered for use as a BC-2000TM substrate and utilizes the same proven high- T_g multifunctional resin system as N4000-6 (FC), which is ideal for a number of demanding applications including high-layer count backplanes and high-density interconnects.

what you need... when you need it... where you need it...



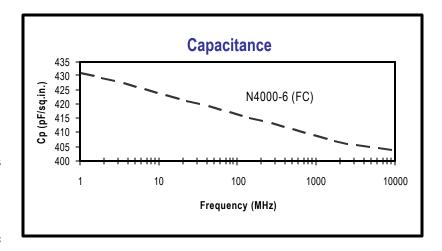
N4000-6 (FC) BC®

Buried Capacitance, High-Tg
Multifunctional Epoxy Laminate &
Buried Capacitance, Fast Cure, High-Tg
Multifunctional Epoxy Laminate &

The N4000-6 (FC) series has robust thermal properties to withstand extreme operating temperatures and multiple thermal excursions or PCB rework operations. This product's performance through hotair solder leveling, IR solder fusion, wave soldering, vapor phase soldering, and thermal shock testing is outstanding.

N4000-6 BC® and N4000-6 FC BC® are 2mil (50µm) dielectric BC-2000 $^{\rm TM}$ buried capacitance substrate s. As you would expect from a high-Tg material, N4000-6 (FC) BC® is targeted for use in fine-line multilayers, surface-mount multilayers, and large-format backplanes. These materials are effective for BGA, MCM-L, and CSP component attachment N4000-6 (FC) BC® is an ideal solution for distributed capacitance functions for telecommunications, wireless handsets, and other high frequency applications. N4000-6 (FC) BC® is provided with either Flip Double-Treat or RTFoil® to provide the most consistent electrostatic capacitance.

As with all Park / Nelco materials, the N4000-6 (FC) and N4000-6 (FC) BC® are vacuum laminated. N4000-6 (FC) is available in a wide variety of constructions, copper weights and glass styles, and is ideally suited for constructions featuring N4000-6 (FC) BC® buried capacitance layers. It is also available in standard copper, double-treat copper and our RTFoil® Laminate.

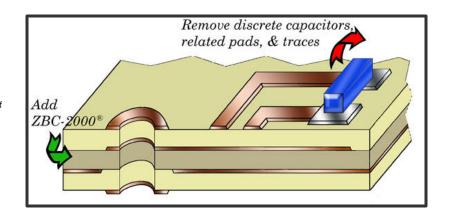


Key Engineering Values		
	N4000-6 BC®	N400-6 FC BC®
X / Y CTE (ppm / °C)[40 to 125°C]	12 - 16	12 – 16
Z-Axis Expansion (%) [50 to 260°C]	3.9	4.1
Tg by DSC (°C)	175	175
Dielectric Constant (.002" 106)		
@ 1KHz	4.2	4.2
@ 1 MHz	3.8	3.8
@ 2.5 GHz	3.6	3.6

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